

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Bruce J. Freyman, et al.  
 Assignee: Amkor Electronics, Inc.  
 Title: MOLD RUNNER REMOVAL FROM A SUBSTRATE BASED  
 PACKAGED ELECTRONIC DEVICE

Serial No.: 08/214,339 Filed: March 16, 1994

Examiner: Decker, R. Group Art Unit: 2100

Attorney Docket No.: M-2556 US

JUL 23 1996

GROUP 2100

San Jose, California  
 July 12, 1996

COMMISSIONER OF PATENTS AND TRADEMARKS  
 Washington, D. C. 20231

## RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action mailed April 18, 1996,  
 please amend the above-identified application as follows.

## IN THE CLAIMS

Please cancel Claims 15-22.

Please amend Claims 1-14 as follows:

1. (AMENDED) A substrate-based packaged electronic  
 device, comprising:

a substrate having first and second surfaces[,  
 wherein:]

a degating region [is formed] on the first surface of  
 the substrate;

a degating region material on the degating region;  
 [and]

a structure for making external electrical connection  
from the substrate-based packaged electronic device [is  
formed] on the second surface of the substrate;

an electronic device attached to the first surface of  
 the substrate, the electronic device being electrically  
 connected to the structure for making external electrical  
 connection; and

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USSN 08/214,339